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Patent

MAY 1 1 2006

Customer No.: 31561
Docket No.:11530-US-PA
Application No.: 10/709,954

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant Application No.

: Ho et al. : 10/709,954

Filed For

: June 9, 2004 : ELECTRICAL PACKAGE CAPABLE OF INCREASING THE DENSITY OF BONDING PADS AND FINE CIRCUIT

LINES INSIDE A INTERCONNECTION

: 2826

Examiner

Art Unit

: WILLIAMS, ALEXANDER O.

<u>TRANSMITTAL LETTER</u> +1-571-273-2885 (Via fax: 1+2 pages)

Assistant Commissioner for Patents Alexandria, VA 22314

Dear Sir,

PAGE 1/1 'RCVD AT 5/11/2006 11:21:35 PM [Eastern Daylight Time] \* SVR:USPTO-EFXRF-2/6 \* DNIS:2738300 \* CSID: \* DURATION (mm-es):02:32

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